

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6214xxxxPR-G

Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.334	Silicon	6300	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	24.392	Copper	460200	7440-50-8
	0.016	Tin	300	7440-31-5
	0.218	Silver	4100	7440-22-4
Die attach(1)	0.126	Silver	2400	7440-22-4
	0.032	Epoxy	600	—
Die attach(2)	0.086	Epoxy	1600	—
	0.072	Silica	1400	60676-86-0
Bonding wire	0.069	Gold	1300	7440-57-5
Resin	23.704	Silica	447200	60676-86-0
	1.934	Epoxy resin	36500	—
	1.396	Phenol resin	26300	—
	0.378	Metal hydroxide	7100	—
Plating	0.400	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."

* The composition for the die attach types is either (1) or (2).